EAST SEARCH An Paper no. 3

r =		/ P	V //(·
L Number	Hits	Search Text	DB	Time stamp
1	8	("4149310" "5249101" "5903046")[pn]	USPAT;	2001/06/11
	1		US-PGPUB;	20:31
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	low with modulus with high with enlongat\$	USPAT;	2001/06/07
		with dielectric	US-PGPUB	18:55
	0		USPAT;	2001/06/07
ł		same dielectric	US-PGPUB	18:56
-	0	modulus with enlongat\$ with dielectric	USPAT;	2001/06/07
ı	1	modulus with chitoligaty with dielectiff	US-PGPUB	18:56
_	21	modulus with strain with dielectric	USPAT;	2001/06/07
		moddids with strain with dielectric	1	
_	41	modulus with stress with dielectric	US-PGPUB	18:57
_	41	modulus with stress with dielectric	USPAT;	2001/06/07
_	83	thormal add ownersion add coefficient	US-PGPUB	19:19
-	83		USPAT;	2001/06/07
		with dielectric and (257/\$ 438/\$)	US-PGPUB	20:24
-	1	5841193.pn.	USPAT;	2001/06/07
			US-PGPUB	20:30
-	9	("4630096" "4827328" "4860166"	USPAT	2001/06/07
		"4907062" "5049980" "5091769"		20:24
		"5111278" "5250843" "5315486").PN.		
-	2	5841193.URPN.	USPAT	2001/06/07
				20:24
_	30	FR4 adj circuit adj board	USPAT;	2001/06/07
			US-PGPUB	20:37
_	554	(printed adj circuit adj board PCB) same	USPAT;	2001/06/07
	334	solder adj balls and (257/\$.ccls.	US-PGPUB	20:39
		438/\$.ccls.)	05 FGF0B	20.39
_	50	FR4 adj printed adj circuit adj board	HCDATT.	2001/06/07
_	30	I The adj princed adj cricuit adj board	USPAT;	2001/06/07
	1 200		US-PGPUB	21:05
-	202	eichelberger.in.	USPAT;	2001/06/07
		-1-1-11	US-PGPUB	21:06
-	40	eichelberger.in. and (257/\$ 438/\$)	USPAT;	2001/06/07
	1	, , , , , , , , , , , , , , , , , , , ,	US-PGPUB	21:09
-	0	(eichelberger.in. and (257/\$ 438/\$)) and	USPAT;	2001/06/07
		enlongat\$	US-PGPUB	21:09
-	0	eichelberger.in. and enlongat\$	USPAT;	2001/06/07
	1		US-PGPUB	21:11
-	14	eichelberger.in. and thermal adj	USPAT;	2001/06/07
		expansion	US-PGPUB	21:49
_	0	(eichelberger.in. and thermal adj	USPAT;	2001/06/07
		expansion) and modulus	US-PGPUB	21:12
-	0	(eichelberger.in. and thermal adj	USPAT;	2001/06/07
		expansion) and modulus	US-PGPUB	21:12
_	288	expansion same modulus same dielectric	USPAT;	2001/06/07
			US-PGPUB	21:49
_	47	(expansion same modulus same dielectric)	USPAT;	2001/06/07
	1	and (257/\$ 438/\$)	US-PGPUB	22:27
_	17	low adj modulus same (CTE expansion	USPAT;	2001/06/07
	'	enlongation fracute) same dielectric	US-PGPUB	22:29
_	19	low adj modulus same (CTE expansion	1	2001/06/07
-	19		USPAT;	
	_	enlongation fracture) same dielectric	US-PGPUB	22:33
-	2	(low adj modulus same (CTE expansion	USPAT;	2001/06/07
		enlongation fracture) same dielectric)	US-PGPUB	22:35
		not (low adj modulus same (CTE expansion		<u> </u>
		enlongation fracute) same dielectric)		
-	0	low adj modulus same high adj enlongation	USPAT;	2001/06/07
			US-PGPUB	22:35
-	0	low adj modulus same enlongation	USPAT;	2001/06/07
		-	US-PGPUB	22:35
	l ol	low adj modulus and enlongation	EPO; JPO;	2001/06/07
			DERWENT;	22:36
			IBM TDB	22.30
_	555	low adj modulus and fracture	USPAT;	2001/06/07
_	335	Tow adj modulus and liacture	•	
	1.0	land and madeline and frontier	US-PGPUB	22:36
-	18	low adj modulus and fracture	EPO; JPO;	2001/06/07
			DERWENT;	22:36
			IBM TDB	1

-	64	low adj modulus same fracture	USPAT;	2001/06/07
	611	lov odd modulus same slovenski sa	US-PGPUB	22:46
-	611	low adj modulus same elongation	USPAT; US-PGPUB	2001/06/07
_	5	low adj modulus same elongation same	USPAT;	2001/06/07
		dielectric	US-PGPUB	22:48
_	5		EPO; JPO;	2001/06/07
		dielectric	DERWENT;	22:52
			IBM TDB	
_	51	modulus and elongation and dielectric	EPO; JPO;	2001/06/07
			DERWENT;	22:52
			IBM TDB	
-	1427	modulus and elongation and dielectric	USPAT;	2001/06/07
			US-PGPUB	22:52
-	247	modulus same elongation same dielectric	USPAT;	2001/06/07
	6	(modulus some elementian some dielement	US-PGPUB	22:52
-	•	(modulus same elongation same dielectric) and (257/\$ 438/\$)	USPAT;	2001/06/07
1_	699	acrylated adj urethane	US-PGPUB USPAT;	23:20
	055	acryrated adj drethame	US-PGPUB	23:20
_	8	(acrylated adj urethane) and (257/\$	USPAT;	2001/06/07
		(438/\$)	US-PGPUB	23:39
-	0	lenght with displac\$ and (257/\$ 438/\$)	USPAT	2001/06/08
				00:24
-	79	long with displac\$ and (257/\$ 438/\$)	USPAT	2001/06/08
				00:42
-	246	length with displac\$ and (257/\$ 438/\$)	USPAT	2001/06/08
				00:44
-	18	length with displac\$ with (wir\$ conductor	USPAT	2001/06/08
	00	interconnect) and (257/\$ 438/\$)		20:53
_	23	, , , , , , , , , , , , , , , , , , ,	USPAT;	2001/06/08
		interconnect) and (257/\$ 438/\$)	US-PGPUB;	13:40
ļ			EPO; JPO;	
			DERWENT; IBM TDB	
-	1	5903046.pn. and modulus	USPAT;	2001/06/08
			US-PGPUB;	16:33
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	5249101.pn. and (elongation fracture)	USPAT;	2001/06/08
			US-PGPUB;	16:52
			EPO; JPO;	
			DERWENT;	
1_	0	F240101 pp and dialectric	IBM TDB	2001/06/00
		5249101.pn. and dielectric	USPAT; US-PGPUB;	2001/06/08
			EPO; JPO;	10.32
			DERWENT;	
			IBM TDB	
-	0	5249101.pn. and insulator	USPAT;	2001/06/08
		•	US-PGPUB;	16:52
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
-	4	acrylated adj urethane with dielectric	USPAT;	2001/06/08
			US-PGPUB;	16:55
			EPO; JPO;	
			DERWENT;	
_	0	(acrylated adj urethane with dielectric)	IBM TDB USPAT;	2001/06/08
		and elongation	US-PGPUB;	17:31
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	602	modulus with copper	USPAT;	2001/06/08
			US-PGPUB;	17:32
			EPO; JPO;	
			DERWENT;	
L			IBM TDB	

	·	T		1 0 0 0 1 6 5 1 5 5
-	0	modulus with copper adj interconnect	USPAT; US-PGPUB;	2001/06/08 17:32
			EPO; JPO;	17.32
			DERWENT;	
			IBM TDB	
-	12	modulus with copper adj wire	USPAT;	2001/06/08
	1		US-PGPUB; EPO; JPO;	17:36
	1		DERWENT;	
			IBM TDB	
-	49	(modulus with copper) and (257/\$ 438/\$)	USPAT;	2001/06/08
			US-PGPUB;	20:26
	1		EPO; JPO; DERWENT;	
			IBM TDB	
-	13	(("Young's" "young") with modulus with	USPAT;	2001/06/08
		copper) and (257/\$ 438/\$)	US-PGPUB;	20:28
			EPO; JPO;	
			DERWENT;	
_	10	(("Young's" "young's") with modulus with	IBM TDB USPAT;	2001/06/08
	13	copper) and (257/\$ 438/\$)	US-PGPUB;	20:30
			EPO; JPO;	= 3.30
1	<u> </u>		DERWENT;	
			IBM TDB	
-	13	(USPAT;	2001/06/08
		copper) and (257/\$ 438/\$)	US-PGPUB;	20:31
			EPO; JPO; DERWENT;	
			IBM TDB	
-	23	3	USPAT;	2001/06/08
		interconnect) and (257/\$ 438/\$)	US-PGPUB;	21:15
			EPO; JPO;	
			DERWENT; IBM TDB	
_	12	expansion with (wir\$ conductor	USPAT;	2001/06/08
	12	interconnect) with displac\$ and (257/\$	US-PGPUB;	21:35
		438/\$)	EPO; JPO;	
			DERWENT;	
_	1 -7	ovnancion with /wine conductor	IBM TDB	2001/06/09
_	17	expansion with (wir\$ conductor interconnect) same displac\$ and (257/\$	USPAT; US-PGPUB;	2001/06/08
		438/\$)	EPO; JPO;	21.45
			DERWENT;	
			IBM TDB	
_	5	(expansion with (wir\$ conductor	USPAT;	2001/06/08
		interconnect) same displac\$ and (257/\$	US-PGPUB;	21:41
		438/\$)) not (expansion with (wir\$ conductor interconnect) with displac\$ and	EPO; JPO; DERWENT;	
		(257/\$ 438/\$))	IBM TDB	
_	15	expansion same (wir\$ conductor	USPAT;	2001/06/08
		interconnect) same length same displac\$	US-PGPUB;	21:49
		and (257/\$ 438/\$)	EPO; JPO;	
			DERWENT; IBM TDB	
_	11	(expansion same (wir\$ conductor	USPAT;	2001/06/08
		interconnect) same length same displac\$	US-PGPUB;	21:51
		and (257/\$ 438/\$)) not ((expansion with	EPO; JPO;	
		(wir\$ conductor interconnect) same	DERWENT;	
		displac\$ and (257/\$ 438/\$)) not	IBM TDB	
		(expansion with (wir\$ conductor		
		interconnect) with displac\$ and (257/\$ 438/\$))) not (expansion with (wir\$		
		conductor interconnect) same displac\$ and		
		(257/\$ 438/\$))		
-	100	thermal adj expansion with displac\$ and	USPAT;	2001/06/09
		(257/\$ 438/\$)	US-PGPUB;	00:56
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

-	3	5841193.pn.	USPAT;	2001/06/11
			US-PGPUB;	20:30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	